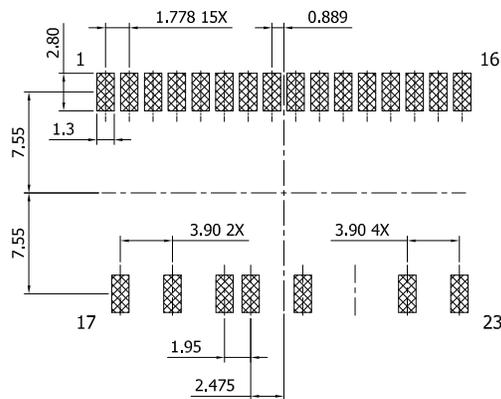
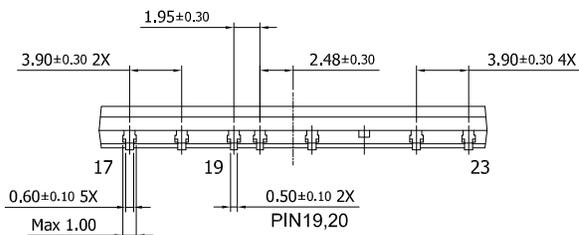
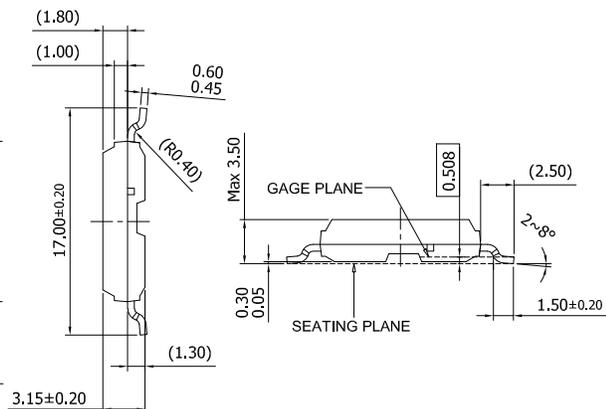
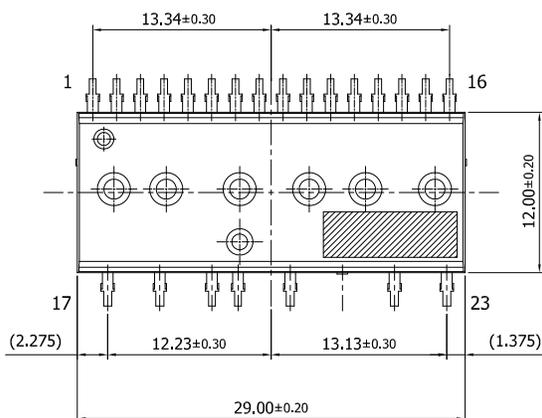
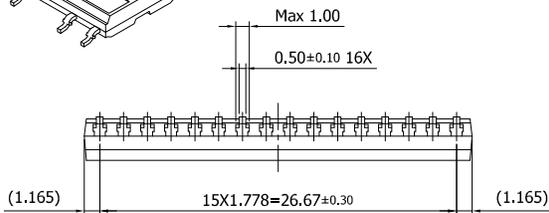
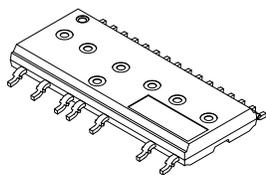


SPM5H-023 / 23LD MODULE, SPM23-BD (Ver1.5) SMD TYPE  
CASE MODEM  
ISSUE A

DATE 28 MAR 2025



LAND PATTERN RECOMMENDATIONS

- NOTES: UNLESS OTHERWISE SPECIFIED  
 A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD  
 B) ALL DIMENSIONS ARE IN MILLIMETERS  
 C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS  
 D) ( ) IS REFERENCE

GENERIC MARKING DIAGRAM\*



- XXXX = Specific Device Code
- A = Assembly Location
- ZZ = Assembly Lot Code
- Y = Year
- WW = Work Week

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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